

# Revision History - AS7C164A

Revision	Details	Date
Rev 1.0	Preliminary datasheet	November 2009
Rev 2	Added 28pin Skinny PDIP(300mil) package option	May 2015

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#### **FEATURES**

■ Fast access time: 12/15 ns■ Low power consumption:

Operating current: 110/100/90/80mA (TYP.)

Standby current : 1mA (TYP.)

Single 5V power supplyAll inputs and outputs TTL compatible

■ Fully static operation

■ Tri-state output

■ Data retention voltage : 2.0V (MIN.)

Green package available

■ Package : 28-pin 300 mil SOJ

28-pin 300 mil Skinny P-DIP

#### **GENERAL DESCRIPTION**

The AS7C164A is a 65,536-bit high speed CMOS static random access memory organized as 8,192 words by 8 bits. It is fabricated using very high performance, high reliability CMOS technology. Its standby current is stable within the range of operating temperature.

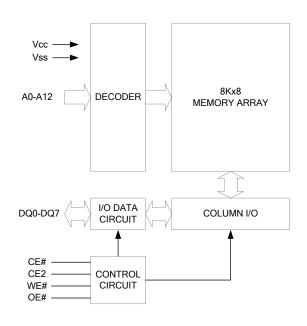
The AS7C164A is well designed for high speed system applications, and particularly well suited for battery back-up nonvolatile memory application.

The AS7C164A operates from a single power supply of 5V and all inputs and outputs are fully TTL compatible

#### **PRODUCT FAMILY**

Product	Operating	Vcc Range	Speed	Power D	Dissipation
Family	Temperature	vcc range	Speed	Standby(IsB1,TYP.)	Operating(Icc,TYP.)
AS7C164A	0 ~ 70°C	4.5 ~ 5.5V	12/15ns	1mA	110/100/90/80mA

#### **FUNCTIONAL BLOCK DIAGRAM**

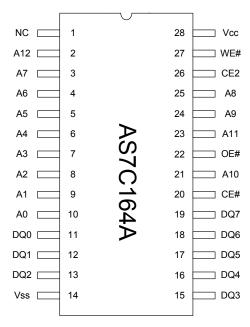


#### PIN DESCRIPTION

SYMBOL	DESCRIPTION
A0 - A12	Address Inputs
DQ0 – DQ7	Data Inputs/Outputs
CE#, CE2	Chip Enable Inputs
WE#	Write Enable Input
OE#	Output Enable Input
Vcc	Power Supply
Vss	Ground
NC	No Connection



#### **PIN CONFIGURATION**



Skinny PDIP/SOJ

#### **ABSOLUTE MAXIMUM RATINGS\***

PARAMETER	SYMBOL	RATING	UNIT
Voltage on Vcc relative to Vss	V <sub>T1</sub>	-0.5 to 6.5	V
Voltage on any other pin relative to Vss	VT2	-0.5 to Vcc+0.5	V
Operating Temperature	TA	0 to 70(C grade)	$^{\circ}\mathbb{C}$
Storage Temperature	Тѕтс	-65 to 150	°C
Power Dissipation	PD	1	W
DC Output Current	Іоит	50	mA

<sup>\*</sup>Stresses greater than those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to the absolute maximum rating conditions for extended period may affect device reliability.

#### **TRUTH TABLE**

MODE	CE#	CE2	OE#	WE#	I/O OPERATION	SUPPLY CURRENT
Standby	Н	Х	Х	Х	High-Z	I <sub>SB1</sub>
Startuby	Х	L	Х	Х	High-Z	I <sub>SB1</sub>
Output Disable	L	Н	Н	Н	High-Z	Icc
Read	L	Н	L	Н	Dout	Icc
Write	L	Н	Х	L	DIN	Icc

Note: H = V<sub>IH</sub>, L = V<sub>IL</sub>, X = Don't care.



#### DC ELECTRICAL CHARACTERISTICS

PARAMETER	SYMBOL	TEST CONDITION	MIN.	TYP. <sup>~4</sup>	MAX.	UNIT
Supply Voltage	Vcc		4.5	5.0	5.5	V
Input High Voltage	V <sub>IH</sub> *1		2.4	-	Vcc+0.5	V
Input Low Voltage	V <sub>IL</sub> *2		- 0.5	-	0.8	V
Input Leakage Current	ILI	$V_{CC} \ge V_{IN} \ge V_{SS}$	- 1	-	1	μA
Output Leakage Current	llo	Vcc ≧ Vouт ≧ Vss, Output Disabled	- 1	-	1	μA
Output High Voltage	Vон	Iон = -1mA	2.4	-	-	V
Output Low Voltage	Vol	IoL = 2mA	-	-	0.4	V
Average Operating Power supply Current	ICC	Cycle time = Min. CE# = V <sub>IL</sub> and CE2 = V <sub>IH</sub> , -12 II/O = 0mA Other pins at V <sub>IH</sub> or V <sub>IL</sub>	-	90 80	160 140	mA mA
Standby Power Supply Current	I <sub>SB1</sub>	CE# $\geq$ Vcc-0.2V or CE2 $\leq$ 0.2V Other pins at 0.2V or Vcc-0.2V	-	1	5	mA

#### Notes:

- 1.  $V_{IH}(max) = V_{CC} + 3.0V$  for pulse width less than 10ns.
- 2. V<sub>IL</sub>(min) = V<sub>SS</sub> 3.0V for pulse width less than 10ns.
- 3. Over/Undershoot specifications are characterized, not 100% tested.
- 4. Typical values are included for reference only and are not guaranteed or tested. Typical valued are measured at  $V_{CC} = V_{CC}(TYP.)$  and  $T_A = 25^{\circ}C$

#### **CAPACITANCE** (TA = $25^{\circ}$ C, f = 1.0MHz)

PARAMETER	SYMBOL	MIN.	MAX	UNIT
Input Capacitance	Cin	-	6	pF
Input/Output Capacitance	C <sub>I/O</sub>	-	8	pF

Note: These parameters are guaranteed by device characterization, but not production tested.

#### **AC TEST CONDITIONS**

Input Pulse Levels	0.2V to Vcc - 0.2V
Input Rise and Fall Times	3ns
Input and Output Timing Reference Levels	1.5V
Output Load	CL = 30pF + 1TTL, IoH/IoL = -4mA/8mA



#### **AC ELECTRICAL CHARACTERISTICS**

#### (1) READ CYCLE

PARAMETER	SYM.	AS7C1	64A-12	AS7C1	64A-15	UNIT
		MIN.	MAX.	MIN.	MAX.	
Read Cycle Time	trc	12	-	15	-	ns
Address Access Time	taa	-	12	-	15	ns
Chip Enable Access Time	<b>t</b> ACE	-	12	-	15	ns
Output Enable Access Time	toe	-	6	-	7	ns
Chip Enable to Output in Low-Z	tclz*	3	-	4	-	ns
Output Enable to Output in Low-Z	tolz*	0	-	0	-	ns
Chip Disable to Output in High-Z	tcHz*	-	6	-	7	ns
Output Disable to Output in High-Z	tonz*	-	6	-	7	ns
Output Hold from Address Change	tон	3	-	3	_	ns

#### (2) WRITE CYCLE

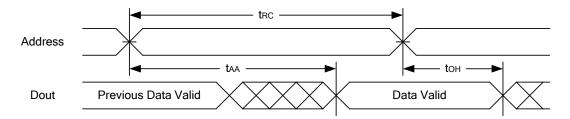
PARAMETER	SYM.	AS7C1	AS7C164A-12 A		AS7C164A-15	
		MIN.	MAX.	MIN.	MAX.	
Write Cycle Time	twc	12	-	15	-	ns
Address Valid to End of Write	taw	10	-	12	-	ns
Chip Enable to End of Write	tcw	10	-	12	-	ns
Address Set-up Time	<b>t</b> as	0	-	0	-	ns
Write Pulse Width	twp	9	-	10	-	ns
Write Recovery Time	twR	0	-	0	-	ns
Data to Write Time Overlap	tow	7	-	8	-	ns
Data Hold from End of Write Time	tон	0	-	0	-	ns
Output Active from End of Write	tow*	3	-	4	-	ns
Write to Output in High-Z	twnz*	-	7	1	8	ns

<sup>\*</sup>These parameters are guaranteed by device characterization, but not production tested.

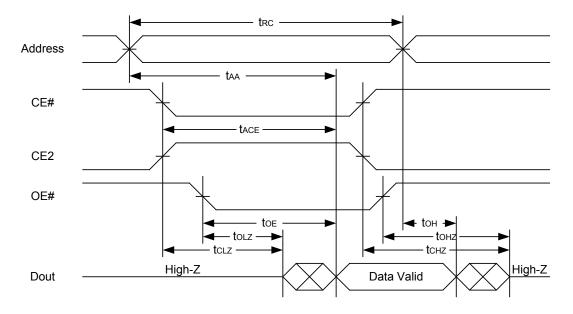


#### **TIMING WAVEFORMS**

#### **READ CYCLE 1** (Address Controlled) (1,2)



#### READ CYCLE 2 (CE# and CE2 and OE# Controlled) (1,3,4,5)

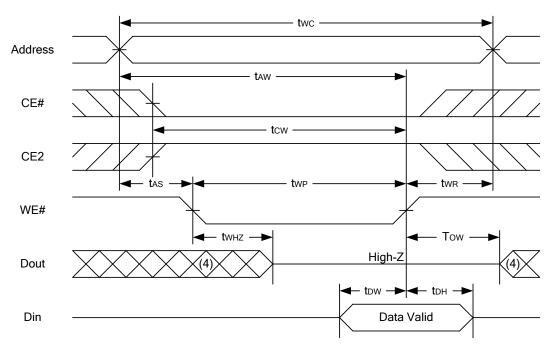


#### Notes:

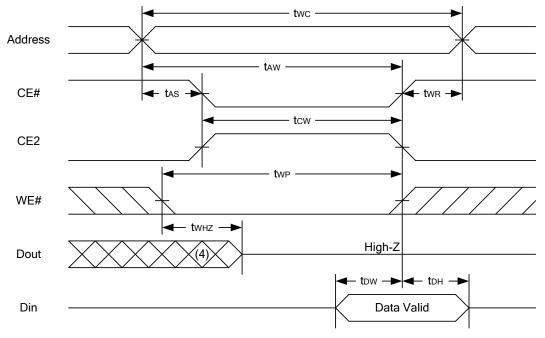
- 1.WE# is high for read cycle.
- 2.Device is continuously selected OE# = low, CE# = low., CE2 = high.
- 3.Address must be valid prior to or coincident with CE# = low, CE2 = high; otherwise tAA is the limiting parameter.
- 4.tclz, tolz, tchz and tohz are specified with CL = 5pF. Transition is measured ±500mV from steady state.
- 5.At any given temperature and voltage condition, t<sub>CHZ</sub> is less than t<sub>CLZ</sub>, t<sub>OHZ</sub> is less than t<sub>OLZ</sub>.



#### WRITE CYCLE 1 (WE# Controlled) (1,2,3,5,6)



#### WRITE CYCLE 2 (CE# and CE2 Controlled) (1,2,5,6)



#### Notes:

- 1.WE#, CE# must be high or CE2 must be low during all address transitions.
- 2.A write occurs during the overlap of a low CE#, high CE2, low WE#.
- 3.During a WE#controlled write cycle with OE# low, twp must be greater than twHz + tpw to allow the drivers to turn off and data to be placed on the bus.
- 4. During this period, I/O pins are in the output state, and input signals must not be applied.
- 5.If the CE#low transition and CE2 high transition occurs simultaneously with or after WE# low transition, the outputs remain in a high impedance state.
- 6.tow and twHz are specified with  $\text{C}_{\text{L}}$  = 5pF. Transition is measured  $\pm 500 \text{mV}$  from steady state.

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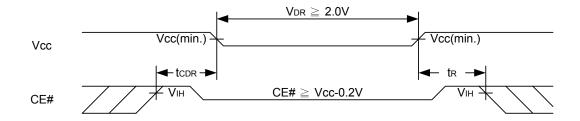
#### **DATA RETENTION CHARACTERISTICS**

PARAMETER	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Vcc for Data Retention		$CE\# \ge V_{CC} - 0.2V$ or $CE2 \le 0.2V$	2.0	-	5.5	V
Data Retention Current		$V_{CC}$ = 2.0V $CE\# \ge V_{CC}$ - 0.2V or $CE2 \le 0.2V$ Others at 0.2V or $V_{CC}$ -0.2V	-	0.6	3	mA
Chip Disable to Data Retention Time	tcdr	See Data Retention Waveforms (below)	0	-	-	ns
Recovery Time	tr		<b>t</b> RC∗	-	-	ns

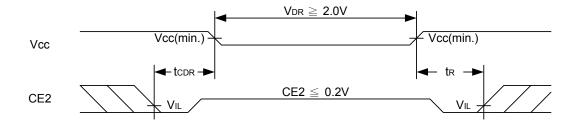
tRC∗ = Read Cycle Time

#### **DATA RETENTION WAVEFORM**

Low Vcc Data Retention Waveform (1) (CE# controlled)

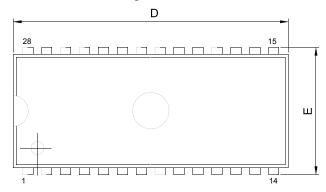


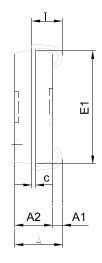
#### Low Vcc Data Retention Waveform (2) (CE2 controlled)

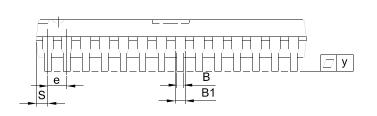


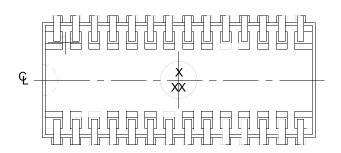


#### 28-pin 300 mil SOJ Package Outline Dimension









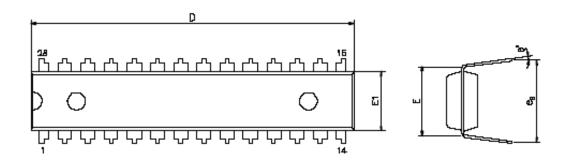
SYM. UNIT	INCH(REF)	MM(BASE)
Α	0.140 (MAX)	3.556 (MAX)
A1	0.026 (MIN)	0.660 (MIN)
A2	0.100±0.005	2.540±0.127
В	0.018±0.003	0.457±0.076
B1	0.028 ±0.003	0.711±0.076
С	0.010±0.003	0.254±0.076
D	0.710±0.010	18.03±0.254
Е	0.337±0.010	8.560±0.254
E1	0.300±0.005	7.620±0.127
е	0.050±0.003	1.270±0.076
L	0.087±0.010	2.210±0.254
S	0.030±0.004	0.762±0.102
Υ	0.003 (MAX)	0.076 (MAX)

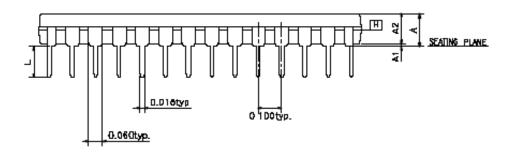
Note: 1.S/E/D dimension is not including mold flash.

2. The end flash in package lengthwise is not more than 10 mils each side.

#### PACKAGE OUTLINE DIMENSION

28 pin 300 mil PDIP Package Outline Dimension





SYMBOLS	MIN.	NOR.	MAX.		
Α	-	_	0.210		
A1	0.015	-	1		
A2	0.125	0.130	0.135		
D	1.385	1.390	1.400		
Е	0.310 BSC				
E1	0.283	0.288	0.293		
L	0.115	0.130	0.150		
€ <sub>B</sub>	e <sub>B</sub> 0.330		0.370		
6° 0		7	15		

UNIT: INCH

NOTE:

1.JEDEC OUTLINE : MS-D15 AH



#### **ORDERING INFORMATION**

Package/Access Time	Temperature	12 ns	15 ns
28-pin 300 mil SOJ	Commercial	AS7C164A-12JCN	AS7C164A-15JCN
28-pin 300 mil Skinny P-DIP	Commercial		AS7C164A-15PCN

Suffix TR = tape and reel

#### **PART NUMBERING SYSTEM**

AS7C		164A	-XX	J/P	C/I	N
SRAM prefix	Voltage: 5V supply	Device Number	Access Time	J = SOJ, 300 mil P= Skinny P-DIP, 300 mil	Temperature Range: $C = 0^{\circ} \sim 70 ^{\circ}C$ $I = -40^{\circ} \sim 85^{\circ} C$	N = Lead Free Part





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